

October 31, 2024
JX Advanced Metals Corporation

Announcement of Organizational Changes

JX Advanced Metals Corporation (President: Hayashi Yoichi; “the Company”) will establish the Advanced Packaging Material Business Promotion Office in the Advanced Technology & Strategy Department, Technology Group, effective November 1, 2024, to promote the development of new businesses.

With the proliferation of generative AI, advanced semiconductors require higher performance, smaller size, and lower power consumption. Significant technological progress in advanced semiconductors has begun not only in front-end processes (forming transistors and wiring on silicon wafers) but also in back-end processes (packaging processes where semiconductor chips are mounted on substrates). Various new approaches to these latter processes have been developed, such as chiplets, which densely integrate multiple chips on a single substrate. In order to further develop these approaches, more advanced materials are required.

One of our flagship products, sputtering targets for semiconductors, is expected to see increased demand in the wiring processes between chips. Additionally, the Company possesses various developmental products that may be adopted in these processes. The newly established office will centralize the JX Advanced Metals Group’s marketing and development functions related to advanced packaging materials, enabling a more agile response to market demands. Furthermore, it will promote new material development and practical application efforts in collaboration with external institutions. Through these activities, the Group aims to expand its product lineup in the semiconductor materials field.

JX Advanced Metals Corporation Old and New Organization Charts

